

WHAT IS CLAIMED IS:

1. A circuit device comprising: circuit elements;  
conductive patterns, to which said circuit elements are affixed  
and forming wiring; and an insulating resin, sealing said  
5 circuit elements and said conductive patterns; wherein

side face of said insulating resin is cut by a laser.

2. The circuit device as set forth in Claim 1, wherein  
an outer peripheral part formed of said insulating resin is  
curved.

10 3. The circuit device as set forth in Claim 1, wherein  
corner parts of an outer peripheral part formed of said  
insulating resin are formed to have an acute angle or an obtuse  
angle.

4. A circuit device manufacturing method comprising the  
15 steps of:

forming, on a conductive foil, conductive patterns  
constituting circuit devices of the same type or different  
types;

20 affixing circuit elements onto said conductive patterns;  
molding with insulating resin so as to cover said circuit  
elements; and

using a laser to cut said insulating resin at locations  
of the outer peripheral part of each circuit device that are

in accordance with a desired shape to thereby perform separation into each of said circuit devices.

5. A circuit device manufacturing method comprising the steps of:

5       forming separation grooves, which are shallower than the thickness of said conductive foil, at regions of the conductive foil except for regions that are to be conductive patterns constituting circuit devices of the same type or different types;

10       affixing circuit elements onto said conductive patterns;  
      molding with insulating resin so as to cover said circuit elements and fill said separation grooves;

      removing said rear surface of said conductive foil until said insulating resin is exposed; and

15       using a laser to cut said insulating resin at locations of the outer peripheral part of each circuit device that are in accordance with a desired shape to thereby perform separation into each of said circuit devices.

6. The circuit device manufacturing method as set forth  
20 in Claim 4 or 5, wherein said laser is used to remove only said insulating resin.

7. The circuit device manufacturing method as set forth in Claim 4 or 5, wherein a carbon dioxide laser is used to remove

said insulating resin.

8. The circuit device manufacturing method as set forth in Claim 4 or 5, wherein said conductive patterns form die pads, bonding pads, and wiring.

5        9. The circuit device as set forth in Claim 4 or 5, wherein an outer peripheral part formed of said insulating resin is formed in a curving manner.

10       10. The circuit device as set forth in Claim 4 or 5, wherein corner parts of an outer peripheral part formed of said insulating resin are formed to have an acute angle or an obtuse angle.

11. A circuit device manufacturing method comprising the steps of:

15       forming, on regions of a conductive foil, conductive patterns constituting at least one circuit device;  
      affixing circuit elements onto said conductive patterns;  
      molding with insulating resin so as to cover said circuit elements;

20       forming through-holes in said insulating resin; and  
      separating into individual circuit devices.

12. A circuit device manufacturing method comprising the steps of:

      forming separation grooves, which are shallower than the

thickness of said conductive foil, at regions of the conductive foil except for regions that are to be conductive patterns constituting at least one circuit device;

affixing circuit elements onto said conductive patterns;

5 molding with insulating resin so as to cover said circuit elements and fill said separation grooves;

forming through-holes in said insulating resin so as to partially expose said separation grooves;

10 removing the remaining thickness portions of said conductive foil at locations at which said separation grooves are formed to expose said insulating resin filled in said separation groove and said through-holes; and

separating into individual circuit devices.

13. The circuit device manufacturing method as set forth  
15 in Claim 11 or 12, wherein a laser is used to form said through-holes.

14. The circuit device manufacturing method as set forth  
in Claim 11 or 12, wherein said laser is reflected by the  
surfaces of said separation grooves and the side faces of said  
20 through-holes are formed vertically.

15. A method of manufacturing a circuit device with  
which a plurality of external electrodes formed of brazing  
material are formed on a rear surface, wherein

the height of said external electrodes are made uniform by irradiation of a laser in the surface direction of said circuit device.